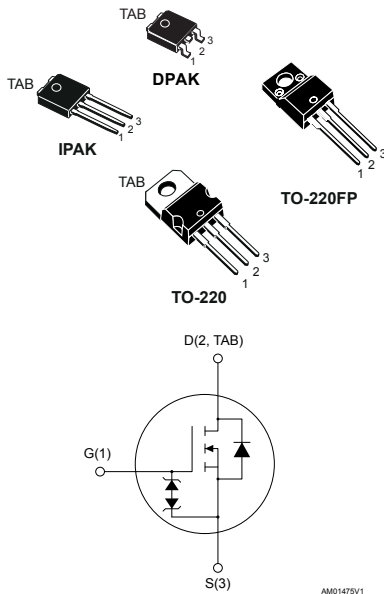


N-channel 650 V, 0.79 Ω typ., 5 A MDmesh M2 Power MOSFETs in DPAK, TO-220FP, TO-220 and IPAK packages



Features

| Order codes | V_{DS} | $R_{DS(on)}$ max. | I_D | Package |
|-------------|----------|-------------------|-------|----------|
| STD9N65M2 | 650 V | 0.90 Ω | 5 A | DPAK |
| STF9N65M2 | | | | TO-220FP |
| STP9N65M2 | | | | TO-220 |
| STU9N65M2 | | | | IPAK |

- Extremely low gate charge
- Excellent output capacitance (C_{OSS}) profile
- 100% avalanche tested
- Zener-protected

Applications

- Switching applications

Description

These devices are N-channel Power MOSFETs developed using the MDmesh M2 technology. Thanks to their strip layout and improved vertical structure, these devices exhibit low on-resistance and optimized switching characteristics, rendering them suitable for the most demanding high-efficiency converters.



Product status link

[STD9N65M2](#)

[STF9N65M2](#)

[STP9N65M2](#)

[STU9N65M2](#)

1 Electrical ratings

Table 1. Absolute maximum ratings

| Symbol | Parameter | Value | | Unit |
|-------------------------|---|--------------------|--------------------|------|
| | | DPAK, TO-220, IPAK | TO-220FP | |
| V_{GS} | Gate-source voltage | ±25 | | V |
| I_D | Drain current (continuous) at $T_C = 25\text{ °C}$ | 5 | 5 ⁽¹⁾ | A |
| I_D | Drain current (continuous) at $T_C = 100\text{ °C}$ | 3.2 | 3.2 ⁽¹⁾ | |
| I_{DM} ⁽²⁾ | Drain current (pulsed) | 20 | | A |
| P_{TOT} | Total power dissipation at $T_C = 25\text{ °C}$ | 60 | 20 | W |
| V_{ISO} | Insulation withstand voltage (RMS) from all three leads to external heat sink ($t = 1\text{ s}$; $T_C = 25\text{ °C}$) | 2.5 | | kV |
| dv/dt ⁽³⁾ | Peak diode recovery voltage slope | 15 | | V/ns |
| dv/dt ⁽⁴⁾ | MOSFET dv/dt ruggedness | 50 | | |
| T_{stg} | Storage temperature range | -55 to 150 | | °C |
| T_J | Operating junction temperature range | | | |

1. Current limited by package.
2. Pulse width is limited by safe operating area.
3. $I_{SD} \leq 5\text{ A}$, $di/dt = 400\text{ A}/\mu\text{s}$; $V_{DS(peak)} < V_{(BR)DSS}$; $V_{DD} = 400\text{ V}$.
4. $V_{DS} \leq 520\text{ V}$.

Table 2. Thermal data

| Symbol | Parameter | Value | | | | Unit |
|------------------------------|-------------------------------------|-------|----------|--------|------|------|
| | | DPAK | TO-220FP | TO-220 | IPAK | |
| $R_{thj-case}$ | Thermal resistance junction-case | 2.08 | 6.25 | 2.08 | | °C/W |
| $R_{thj-pcb}$ | Thermal resistance junction-pcb | 50 | | | | °C/W |
| $R_{thj-amb}$ ⁽¹⁾ | Thermal resistance junction-ambient | | 62.5 | | 100 | °C/W |

1. When mounted on 1 inch² FR-4, 2 Oz copper board.

Table 3. Avalanche characteristics

| Symbol | Parameter | Value | Unit |
|----------|--|-------|------|
| I_{AR} | Avalanche current, repetitive or not repetitive (pulse width limited by T_J max) | 1 | A |
| E_{AS} | Single pulse avalanche energy (starting $T_J = 25\text{ °C}$, $I_D = I_{AR}$; $V_{DD} = 50\text{ V}$) | 105 | mJ |

2 Electrical characteristics

($T_C = 25\text{ °C}$ unless otherwise specified)

Table 4. On/off states

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---------------|-----------------------------------|--|------|------|----------|---------------|
| $V_{(BR)DSS}$ | Drain-source breakdown voltage | $V_{GS} = 0\text{ V}$, $I_D = 1\text{ mA}$ | 650 | | | V |
| I_{DSS} | Zero gate voltage drain current | $V_{GS} = 0\text{ V}$, $V_{DS} = 650\text{ V}$ | | | 1 | μA |
| | | $V_{GS} = 0\text{ V}$, $V_{DS} = 650\text{ V}$, $T_C = 125\text{ °C}$ ⁽¹⁾ | | | 100 | μA |
| I_{GSS} | Gate-body leakage current | $V_{DS} = 0\text{ V}$, $V_{GS} = \pm 25\text{ V}$ | | | ± 10 | μA |
| $V_{GS(th)}$ | Gate threshold voltage | $V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$ | 2 | 3 | 4 | V |
| $R_{DS(on)}$ | Static drain-source on-resistance | $V_{GS} = 10\text{ V}$, $I_D = 2.5\text{ A}$ | | 0.79 | 0.90 | Ω |

1. Defined by design, not subject to production test.

Table 5. Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-------------------------------------|---------------------------------------|--|------|------|------|----------|
| C_{iss} | Input capacitance | $V_{DS} = 100\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0\text{ V}$ | - | 310 | - | pF |
| C_{oss} | Output capacitance | | - | 18 | - | pF |
| C_{rss} | Reverse transfer capacitance | | - | 0.9 | - | pF |
| $C_{oss\text{ eq.}}$ ⁽¹⁾ | Equivalent capacitance energy related | $V_{DS} = 0\text{ to }520\text{ V}$, $V_{GS} = 0\text{ V}$ | - | 109 | - | pF |
| R_g | Intrinsic gate resistance | $f = 1\text{ MHz}$ open drain | - | 6.6 | - | Ω |
| Q_g | Total gate charge | $V_{DD} = 520\text{ V}$, $I_D = 5\text{ A}$ | - | 10.3 | - | nC |
| Q_{gs} | Gate-source charge | $V_{GS} = 0\text{ to }10\text{ V}$ | - | 2.4 | - | nC |
| Q_{gd} | Gate-drain charge | (see Figure 18. Test circuit for gate charge behavior) | - | 4.8 | - | nC |

1. $C_{oss\text{ eq.}}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS} .

Table 6. Switching times

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|--------------|---------------------|---|------|------|------|------|
| $t_{d(on)}$ | Turn-on delay time | $V_{DD} = 325\text{ V}$, $I_D = 2.5\text{ A}$, | - | 7.5 | - | ns |
| t_r | Rise time | $R_G = 4.7\text{ }\Omega$, $V_{GS} = 10\text{ V}$ | - | 6.6 | - | ns |
| $t_{d(off)}$ | Turn-off delay time | (see Figure 17. Test circuit for resistive load switching times and | - | 22.5 | - | ns |
| t_f | Fall time | Figure 22. Switching time waveform) | - | 18 | - | ns |

Table 7. Source-drain diode

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-----------------|-------------------------------|---|------|------|------|---------------|
| I_{SD} | Source-drain current | | - | | 5 | A |
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) | | - | | 20 | A |
| $V_{SD}^{(2)}$ | Forward on voltage | $I_{SD} = 5\text{ A}$, $V_{GS} = 0\text{ V}$ | - | | 1.6 | V |
| t_{rr} | Reverse recovery time | $I_{SD} = 5\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$ (see Figure 19. Test circuit for inductive load switching and diode recovery times) | - | 276 | | ns |
| Q_{rr} | Reverse recovery charge | | - | 1.7 | | μC |
| I_{RRM} | Reverse recovery current | $I_{SD} = 5\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$, $T_J = 150\text{ }^\circ\text{C}$ (see Figure 19. Test circuit for inductive load switching and diode recovery times) | - | 12.5 | | A |
| t_{rr} | Reverse recovery time | | - | 312 | | ns |
| Q_{rr} | Reverse recovery charge | | - | 1.9 | | μC |
| I_{RRM} | Reverse recovery current | | - | 12.4 | | A |

1. Pulse width is limited by safe operating area.
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%.

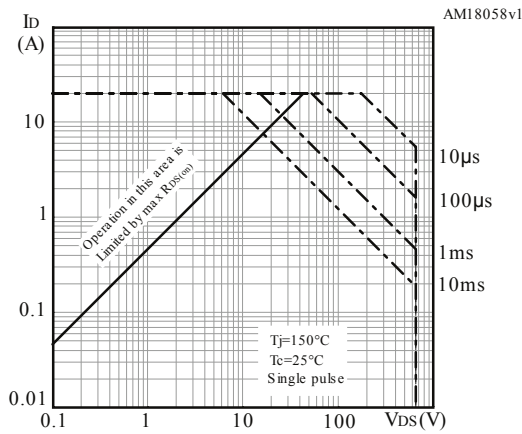
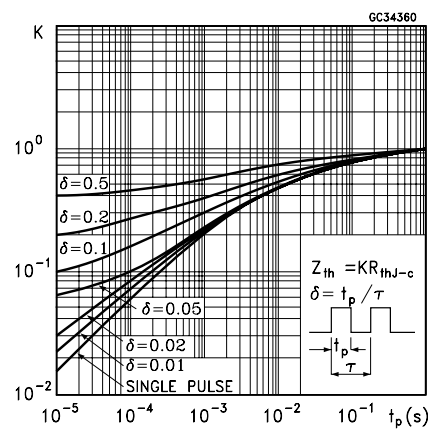
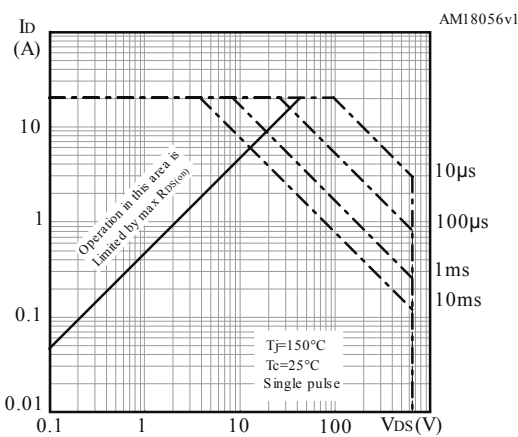
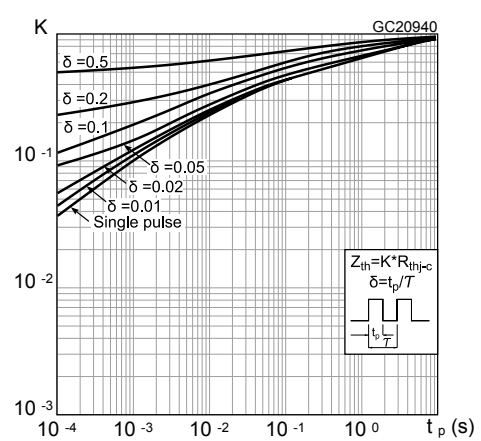
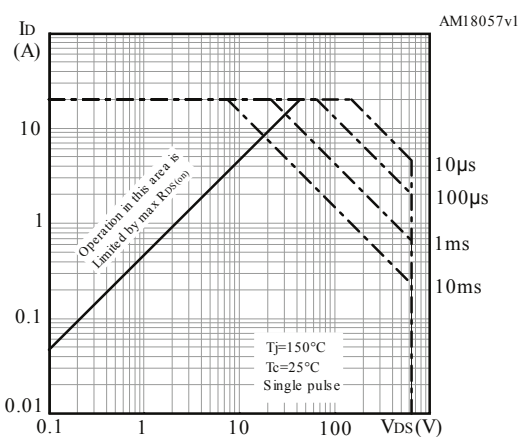
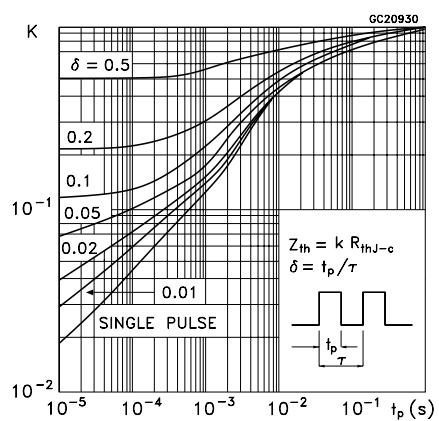
2.1 Electrical characteristics (curves)
Figure 1. Safe operating area for DPAK and IPAK

Figure 2. Thermal impedance for DPAK and IPAK

Figure 3. Safe operating area for TO-220FP

Figure 4. Thermal impedance for TO-220FP

Figure 5. Safe operating area for TO-220

Figure 6. Thermal impedance for TO-220


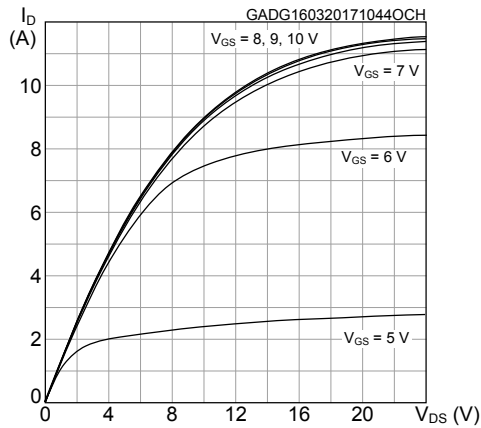
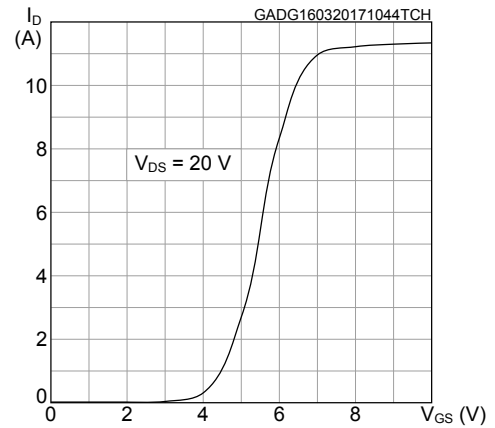
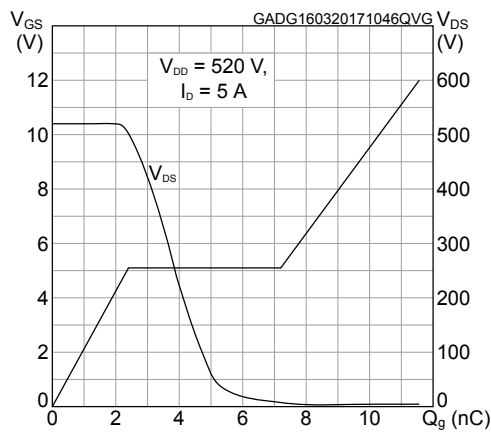
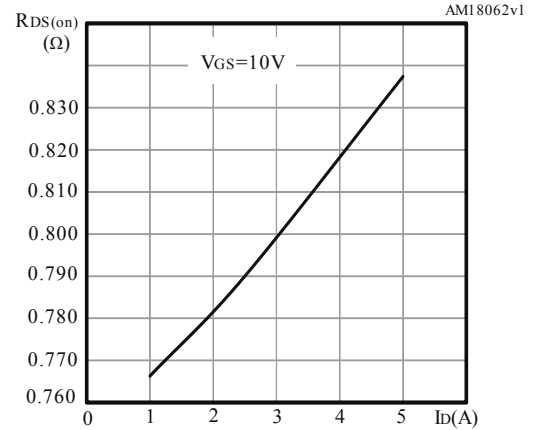
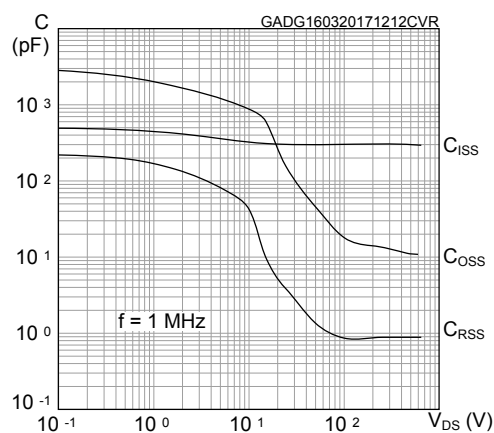
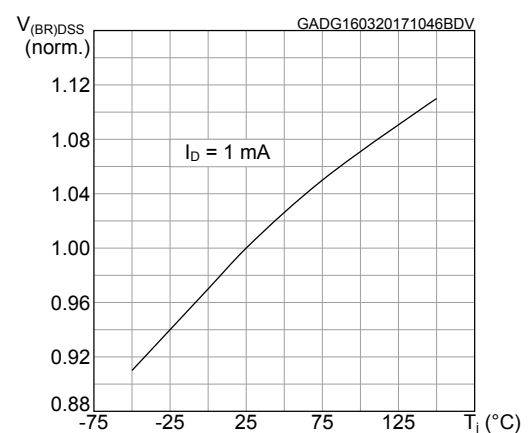
Figure 7. Output characteristics

Figure 8. Transfer characteristics

Figure 9. Gate charge vs gate-source voltage

Figure 10. Static drain-source on-resistance

Figure 11. Capacitance variations

Figure 12. Normalized $V_{(BR)DSS}$ vs temperature


Figure 13. Normalized gate threshold voltage vs temperature

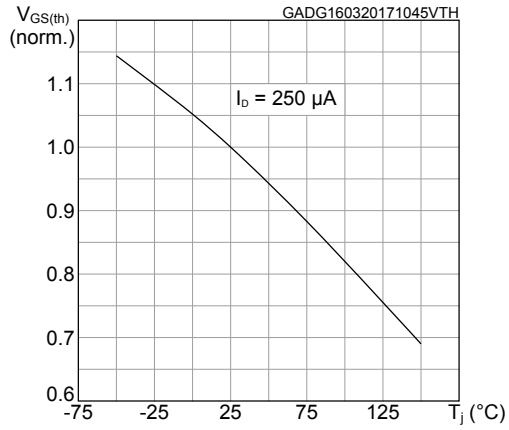


Figure 14. Normalized on-resistance vs temperature

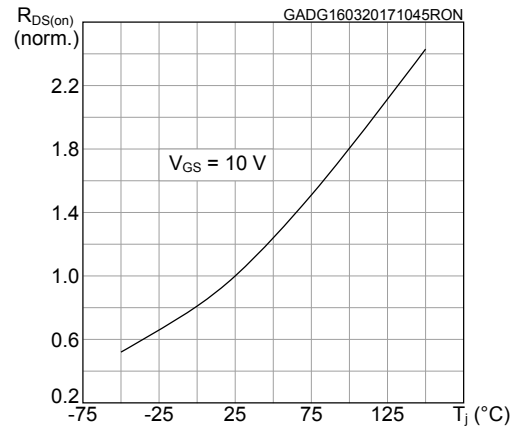


Figure 15. Source-drain diode forward characteristics

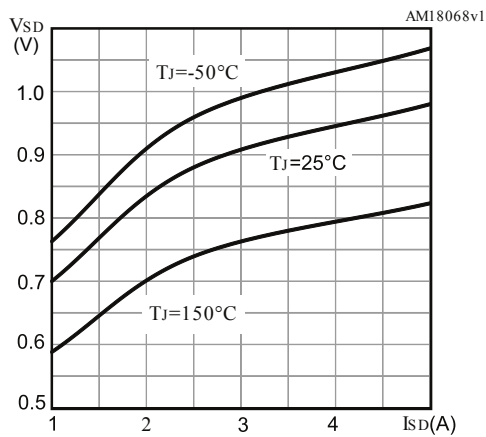
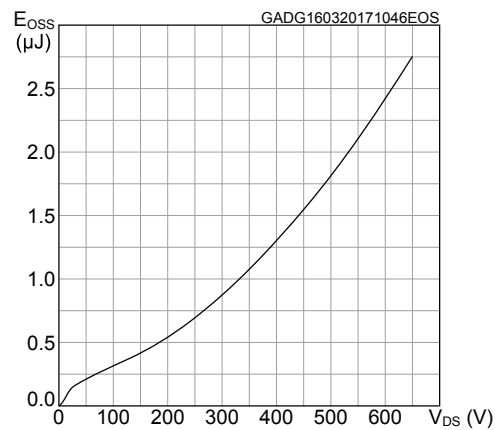
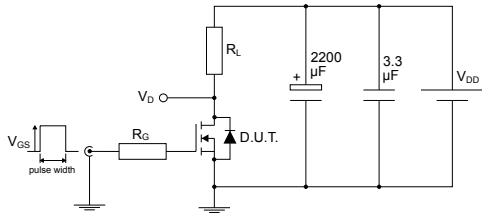


Figure 16. Output capacitance stored energy



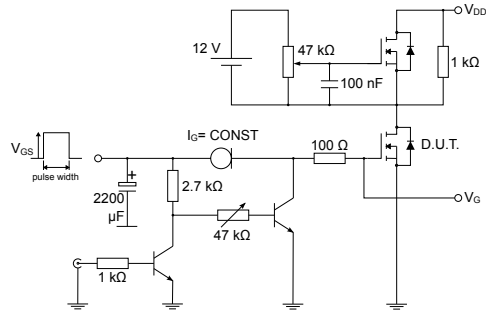
3 Test circuits

Figure 17. Test circuit for resistive load switching times



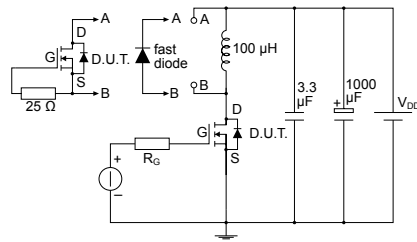
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Figure 18. Test circuit for gate charge behavior



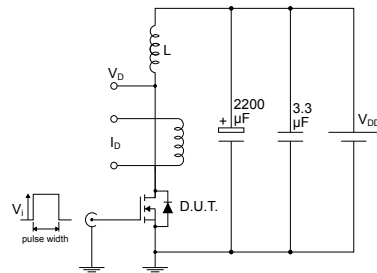
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Figure 19. Test circuit for inductive load switching and diode recovery times



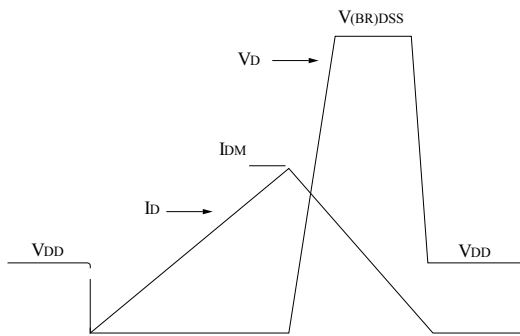
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Figure 20. Unclamped inductive load test circuit



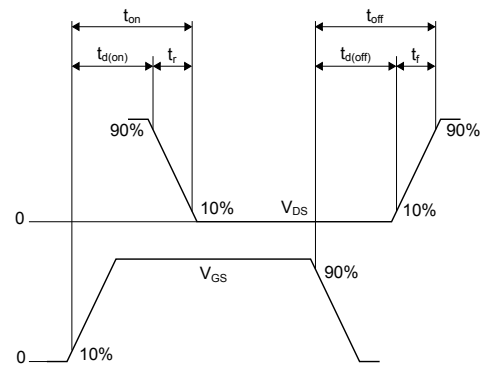
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Figure 21. Unclamped inductive waveform



AM01472v1

Figure 22. Switching time waveform



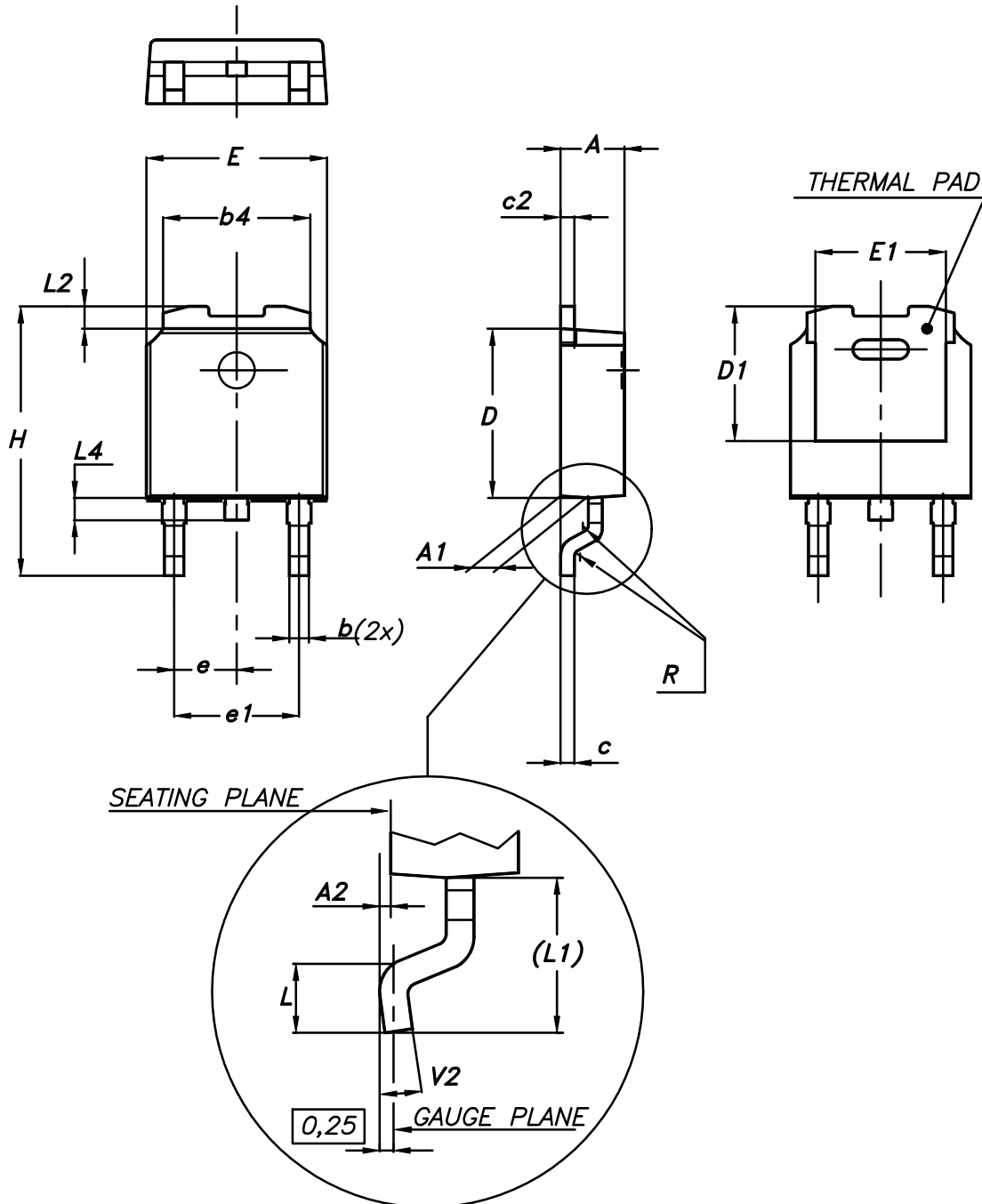
AM01473v1

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 DPAK (TO-252) type A package information

Figure 23. DPAK (TO-252) type A package outline



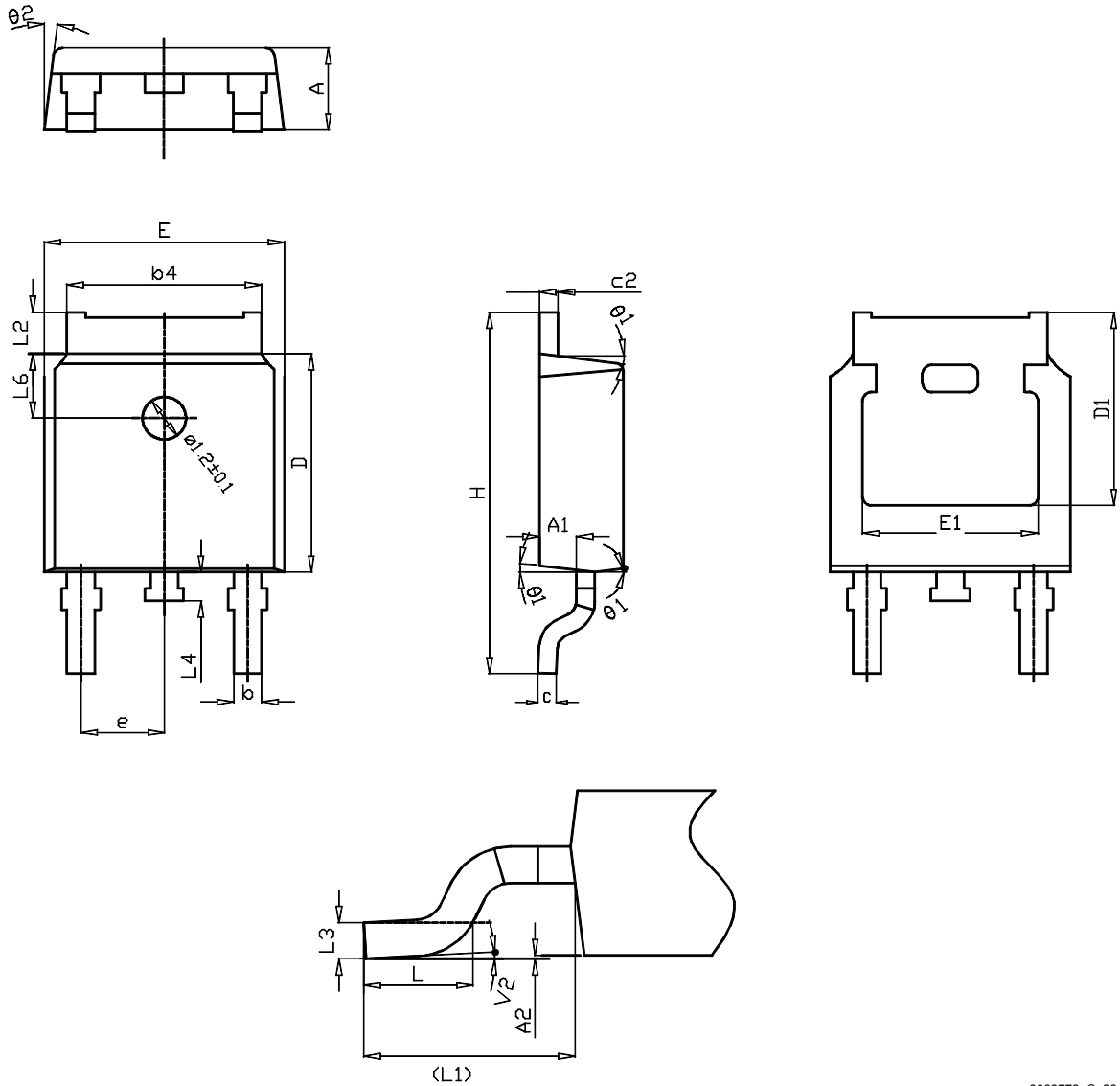
0068772_A_26

Table 8. DPAK (TO-252) type A mechanical data

| Dim. | mm | | |
|------|-------|-------|-------|
| | Min. | Typ. | Max. |
| A | 2.20 | | 2.40 |
| A1 | 0.90 | | 1.10 |
| A2 | 0.03 | | 0.23 |
| b | 0.64 | | 0.90 |
| b4 | 5.20 | | 5.40 |
| c | 0.45 | | 0.60 |
| c2 | 0.48 | | 0.60 |
| D | 6.00 | | 6.20 |
| D1 | 4.95 | 5.10 | 5.25 |
| E | 6.40 | | 6.60 |
| E1 | 4.60 | 4.70 | 4.80 |
| e | 2.159 | 2.286 | 2.413 |
| e1 | 4.445 | 4.572 | 4.699 |
| H | 9.35 | | 10.10 |
| L | 1.00 | | 1.50 |
| (L1) | 2.60 | 2.80 | 3.00 |
| L2 | 0.65 | 0.80 | 0.95 |
| L4 | 0.60 | | 1.00 |
| R | | 0.20 | |
| V2 | 0° | | 8° |

4.2 DPAK (TO-252) type C package information

Figure 24. DPAK (TO-252) type C package outline

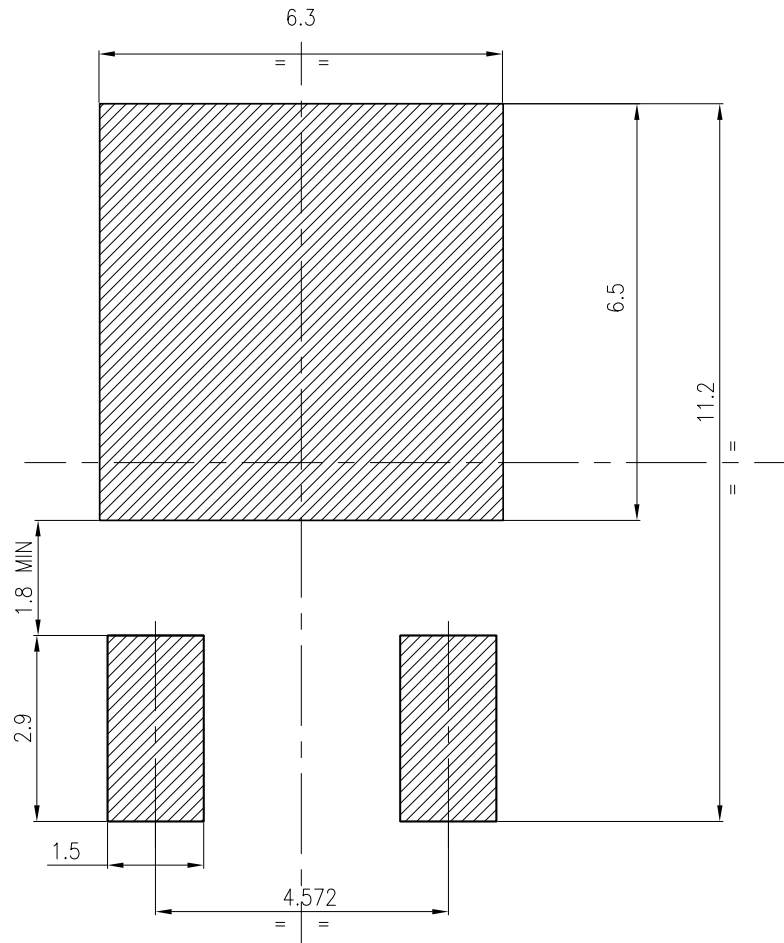


0068772_C_26

Table 9. DPAK (TO-252) type C mechanical data

| Dim. | mm | | |
|------|----------|-------|-------|
| | Min. | Typ. | Max. |
| A | 2.20 | 2.30 | 2.38 |
| A1 | 0.90 | 1.01 | 1.10 |
| A2 | 0.00 | | 0.10 |
| b | 0.72 | | 0.85 |
| b4 | 5.13 | 5.33 | 5.46 |
| c | 0.47 | | 0.60 |
| c2 | 0.47 | | 0.60 |
| D | 6.00 | 6.10 | 6.20 |
| D1 | 5.25 | | |
| E | 6.50 | 6.60 | 6.70 |
| E1 | 4.70 | | |
| e | 2.186 | 2.286 | 2.386 |
| H | 9.80 | 10.10 | 10.40 |
| L | 1.40 | 1.50 | 1.70 |
| L1 | 2.90 REF | | |
| L2 | 0.90 | | 1.25 |
| L3 | 0.51 BSC | | |
| L4 | 0.60 | 0.80 | 1.00 |
| L6 | 1.80 BSC | | |
| θ1 | 5° | 7° | 9° |
| θ2 | 5° | 7° | 9° |
| V2 | 0° | | 8° |

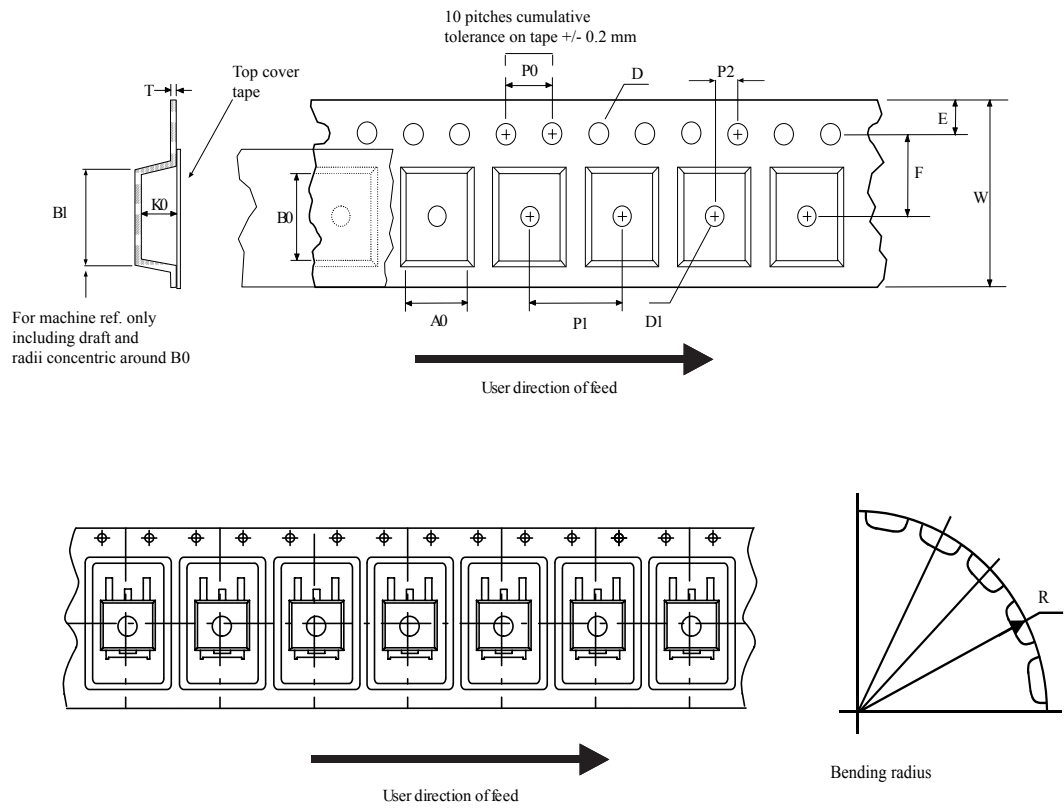
Figure 25. DPAK (TO-252) recommended footprint (dimensions are in mm)



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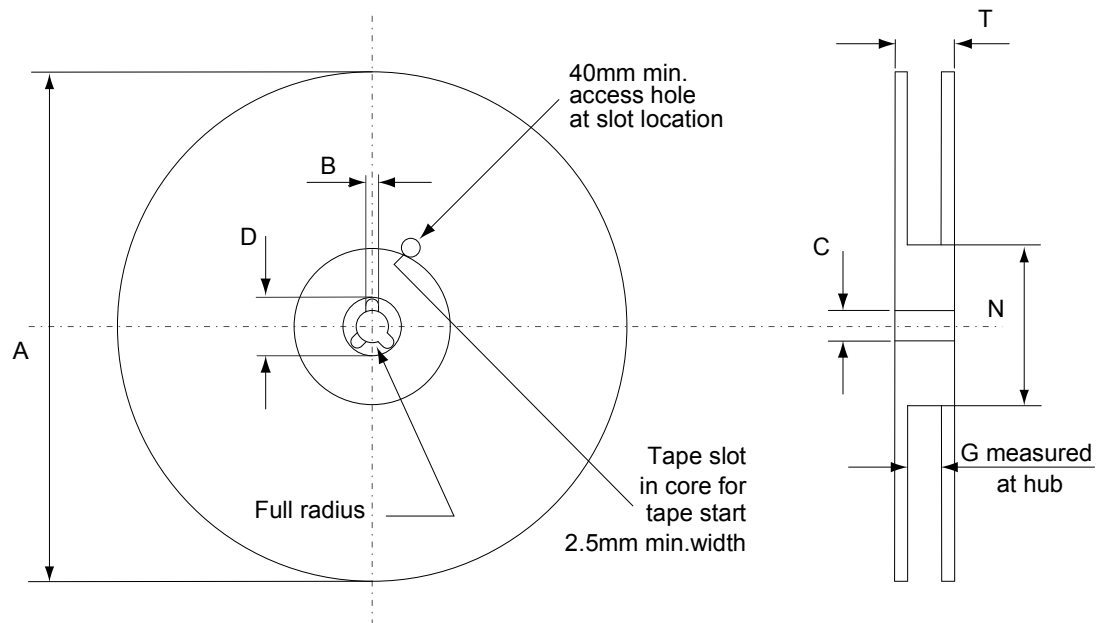
4.3 DPAK (TO-252) packing information

Figure 26. DPAK (TO-252) tape outline



AM08852v1

Figure 27. DPAK (TO-252) reel outline



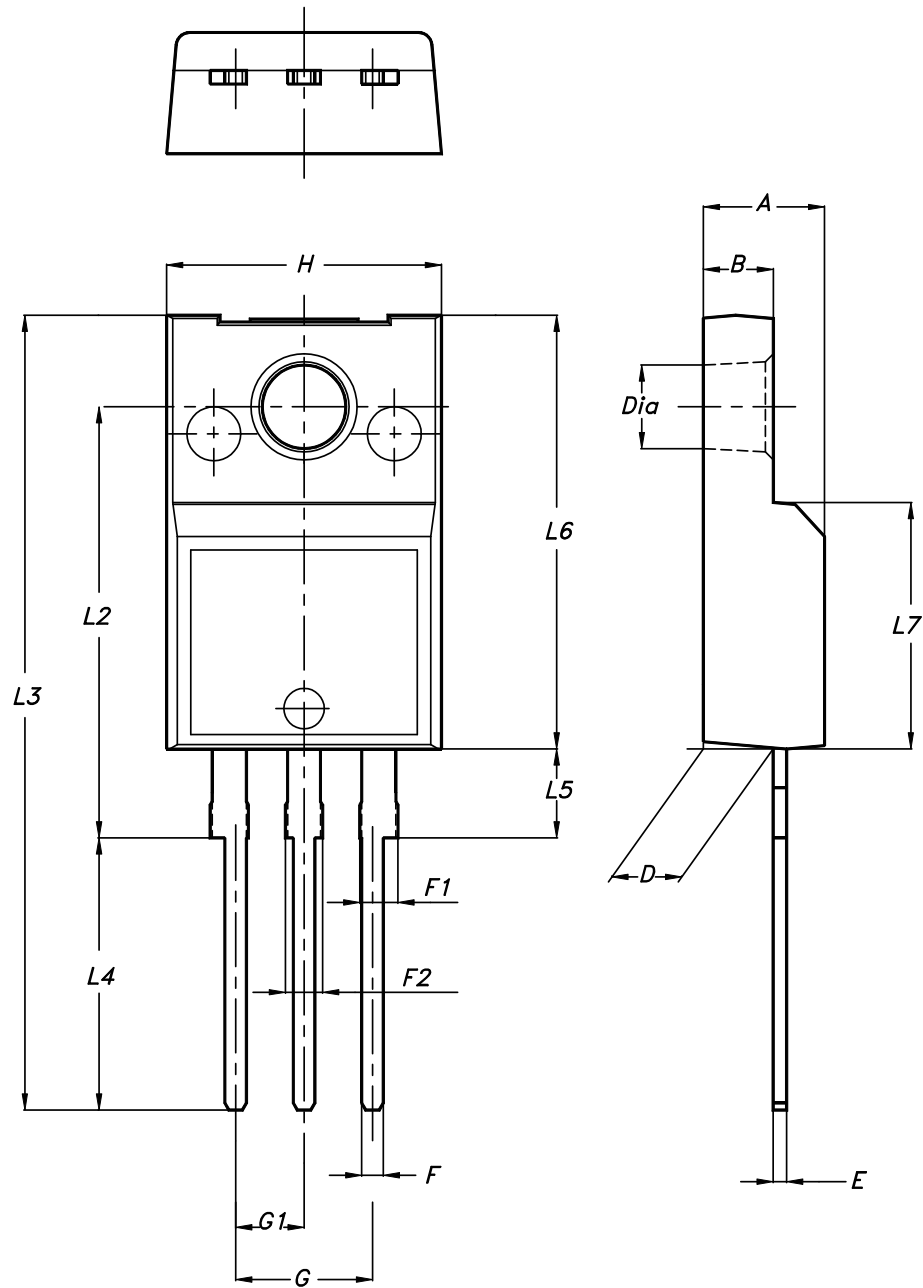
AM06038v1

Table 10. DPAK (TO-252) tape and reel mechanical data

| Tape | | | Reel | | |
|------|------|------|-----------|------|------|
| Dim. | mm | | Dim. | mm | |
| | Min. | Max. | | Min. | Max. |
| A0 | 6.8 | 7 | A | | 330 |
| B0 | 10.4 | 10.6 | B | 1.5 | |
| B1 | | 12.1 | C | 12.8 | 13.2 |
| D | 1.5 | 1.6 | D | 20.2 | |
| D1 | 1.5 | | G | 16.4 | 18.4 |
| E | 1.65 | 1.85 | N | 50 | |
| F | 7.4 | 7.6 | T | | 22.4 |
| K0 | 2.55 | 2.75 | | | |
| P0 | 3.9 | 4.1 | Base qty. | | 2500 |
| P1 | 7.9 | 8.1 | Bulk qty. | | 2500 |
| P2 | 1.9 | 2.1 | | | |
| R | 40 | | | | |
| T | 0.25 | 0.35 | | | |
| W | 15.7 | 16.3 | | | |

4.4 TO-220FP package information

Figure 28. TO-220FP package outline



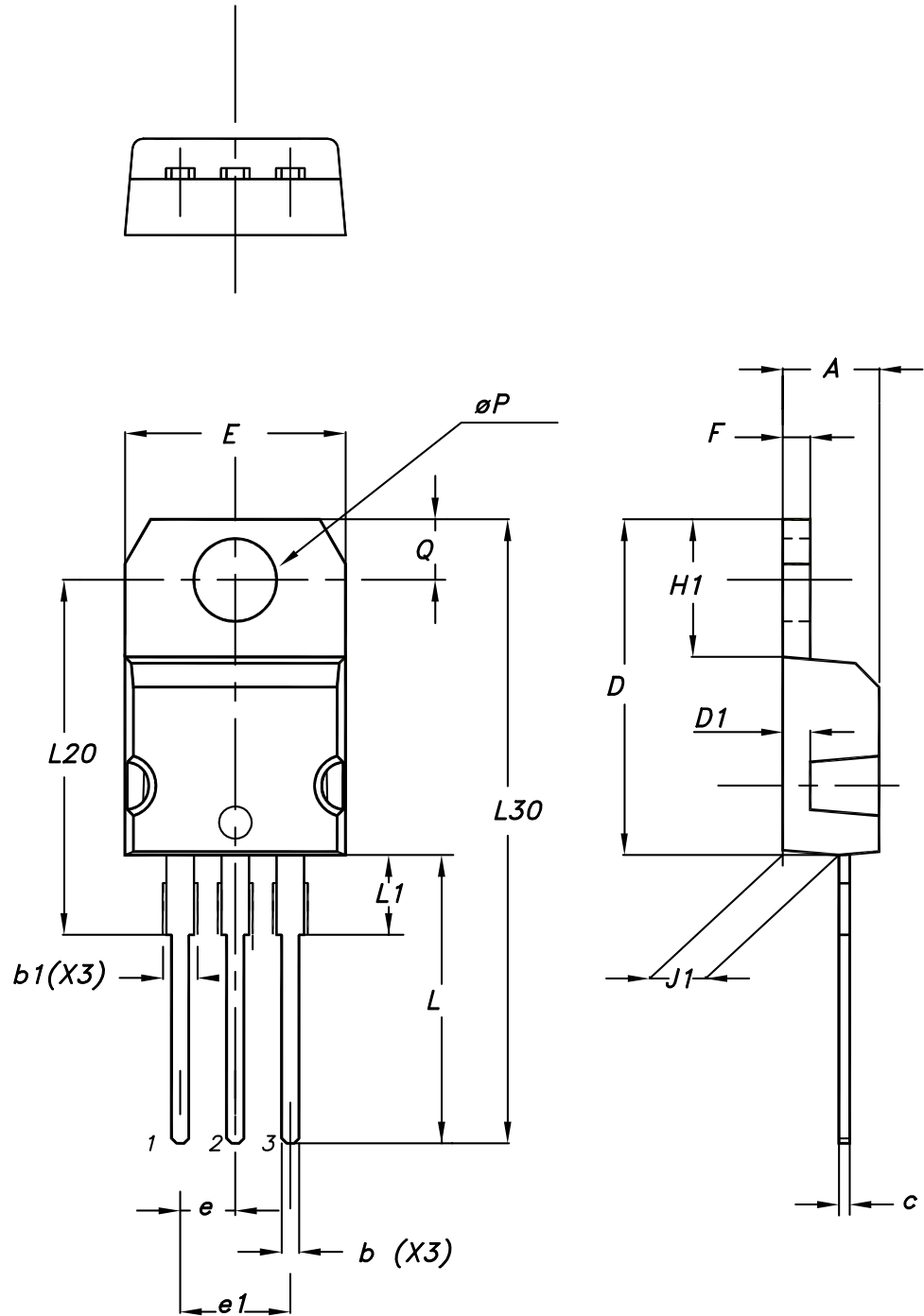
7012510_Rev_13_B

Table 11. TO-220FP package mechanical data

| Dim. | mm | | |
|------|-------|-------|-------|
| | Min. | Typ. | Max. |
| A | 4.40 | | 4.60 |
| B | 2.50 | | 2.70 |
| D | 2.50 | | 2.75 |
| E | 0.45 | | 0.70 |
| F | 0.75 | | 1.00 |
| F1 | 1.15 | | 1.70 |
| F2 | 1.15 | | 1.70 |
| G | 4.95 | | 5.20 |
| G1 | 2.40 | | 2.70 |
| H | 10.00 | | 10.40 |
| L2 | | 16.00 | |
| L3 | 28.60 | | 30.60 |
| L4 | 9.80 | | 10.60 |
| L5 | 2.90 | | 3.60 |
| L6 | 15.90 | | 16.40 |
| L7 | 9.00 | | 9.30 |
| Dia | 3.00 | | 3.20 |

4.5 TO-220 type A package information

Figure 29. TO-220 type A package outline



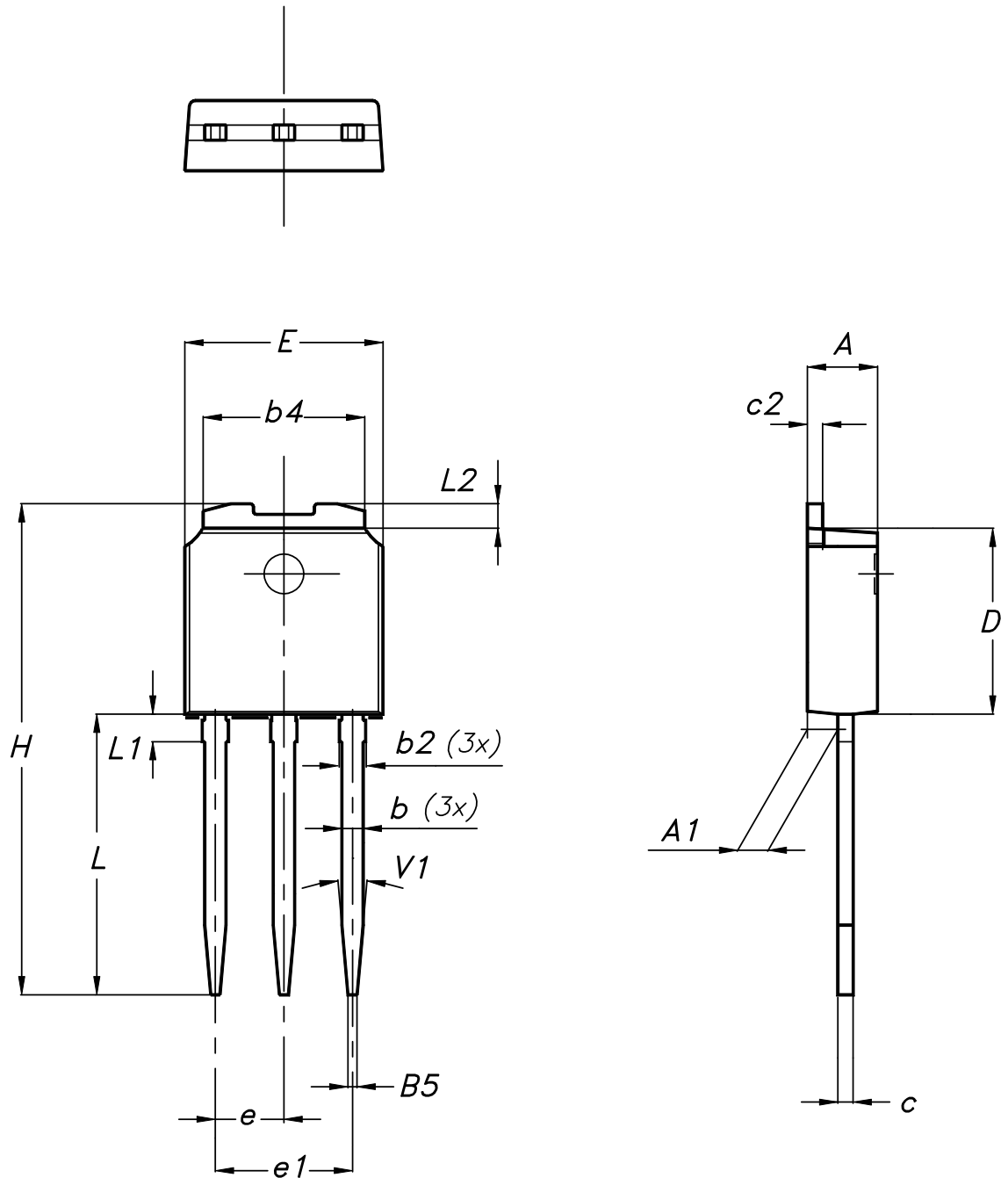
0015988_typeA_Rev_22

Table 12. TO-220 type A package mechanical data

| Dim. | mm | | |
|------|-------|-------|-------|
| | Min. | Typ. | Max. |
| A | 4.40 | | 4.60 |
| b | 0.61 | | 0.88 |
| b1 | 1.14 | | 1.55 |
| c | 0.48 | | 0.70 |
| D | 15.25 | | 15.75 |
| D1 | | 1.27 | |
| E | 10.00 | | 10.40 |
| e | 2.40 | | 2.70 |
| e1 | 4.95 | | 5.15 |
| F | 1.23 | | 1.32 |
| H1 | 6.20 | | 6.60 |
| J1 | 2.40 | | 2.72 |
| L | 13.00 | | 14.00 |
| L1 | 3.50 | | 3.93 |
| L20 | | 16.40 | |
| L30 | | 28.90 | |
| øP | 3.75 | | 3.85 |
| Q | 2.65 | | 2.95 |

4.6 IPAK (TO-251) type A package information

Figure 30. IPAK (TO-251) type A package outline



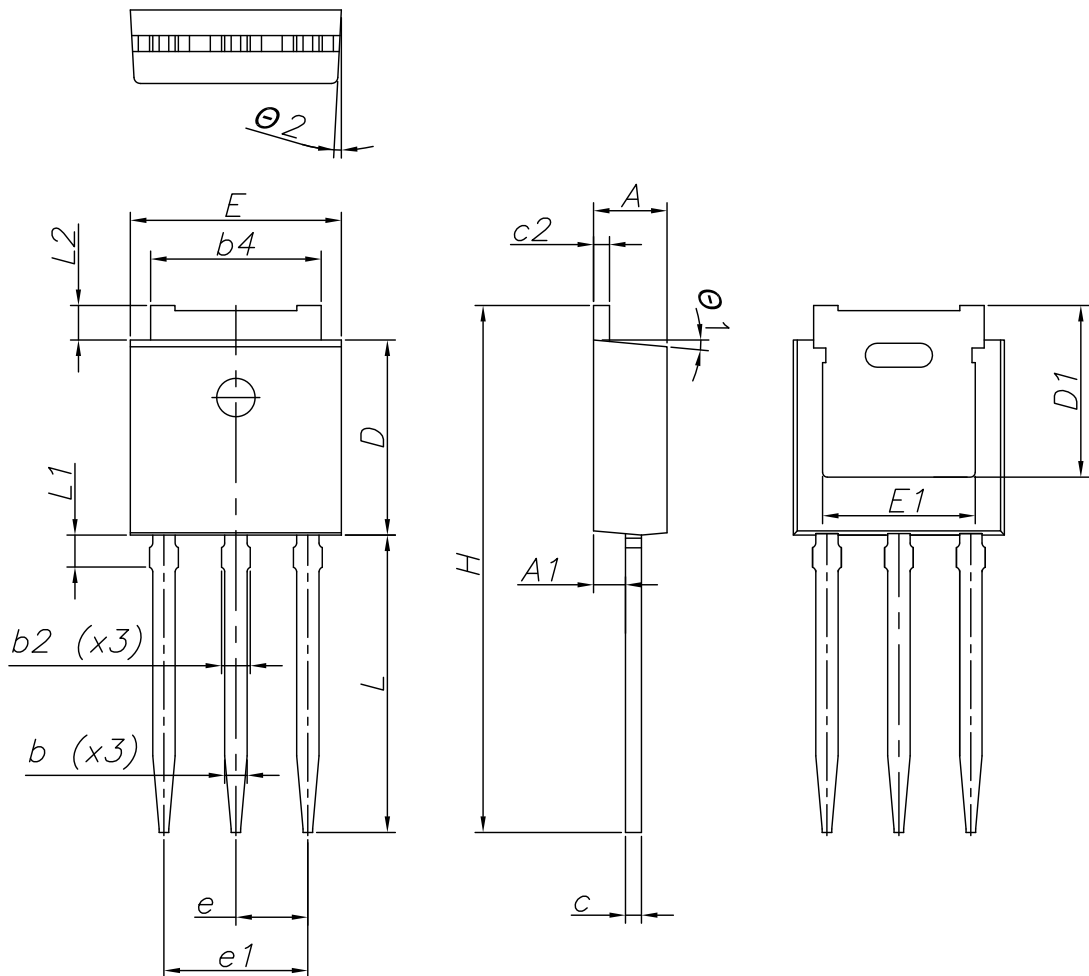
0068771_IK_typeA_rev14

Table 13. IPAK (TO-251) type A package mechanical data

| Dim. | mm | | |
|------|------|-------|------|
| | Min. | Typ. | Max. |
| A | 2.20 | | 2.40 |
| A1 | 0.90 | | 1.10 |
| b | 0.64 | | 0.90 |
| b2 | | | 0.95 |
| b4 | 5.20 | | 5.40 |
| B5 | | 0.30 | |
| c | 0.45 | | 0.60 |
| c2 | 0.48 | | 0.60 |
| D | 6.00 | | 6.20 |
| E | 6.40 | | 6.60 |
| e | | 2.28 | |
| e1 | 4.40 | | 4.60 |
| H | | 16.10 | |
| L | 9.00 | | 9.40 |
| L1 | 0.80 | | 1.20 |
| L2 | | 0.80 | 1.00 |
| V1 | | 10° | |

4.7 IPAK (TO-251) type C package information

Figure 31. IPAK (TO-251) type C package outline



0068771_IK_typeC_rev14

Table 14. IPAK (TO-251) type C package mechanical data

| Dim. | mm | | |
|------|-------|-------|-------|
| | Min. | Typ. | Max. |
| A | 2.20 | 2.30 | 2.35 |
| A1 | 0.90 | 1.00 | 1.10 |
| b | 0.66 | | 0.79 |
| b2 | | | 0.90 |
| b4 | 5.23 | 5.33 | 5.43 |
| c | 0.46 | | 0.59 |
| c2 | 0.46 | | 0.59 |
| D | 6.00 | 6.10 | 6.20 |
| D1 | 5.20 | 5.37 | 5.55 |
| E | 6.50 | 6.60 | 6.70 |
| E1 | 4.60 | 4.78 | 4.95 |
| e | 2.20 | 2.25 | 2.30 |
| e1 | 4.40 | 4.50 | 4.60 |
| H | 16.18 | 16.48 | 16.78 |
| L | 9.00 | 9.30 | 9.60 |
| L1 | 0.80 | 1.00 | 1.20 |
| L2 | 0.90 | 1.08 | 1.25 |
| θ1 | 3° | 5° | 7° |
| θ2 | 1° | 3° | 5° |

5 Ordering information

Table 15. Order codes

| Order code | Marking | Package | Packing |
|------------|---------|----------|---------------|
| STD9N65M2 | 9N65M2 | DPAK | Tape and reel |
| STF9N65M2 | | TO-220FP | Tube |
| STP9N65M2 | | TO-220 | |
| STU9N65M2 | | IPAK | |

Revision history

Table 16. Document revision history

| Date | Version | Changes |
|-------------|---------|---|
| 24-Feb-2014 | 1 | First release. |
| 15-Jul-2014 | 2 | <ul style="list-style-type: none"> – Modified: title, <i>Features</i> and <i>Description</i> – Modified: <i>Figure 5</i> and <i>15</i> – Updated: <i>Figure 28</i> and <i>Table 12</i> – Minor text changes. |
| 19-Jun-2019 | 3 | <p>Removed maturity status indication from cover page. The document status is production data.</p> <p>Updated Section 1 Electrical ratings, Section 2 Electrical characteristics and Section 2.1 Electrical characteristics (curves)</p> <p>Minor text changes.</p> |

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